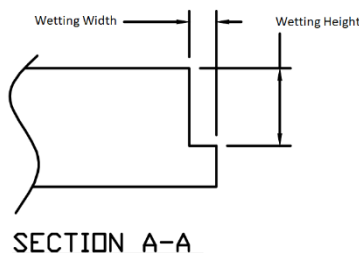
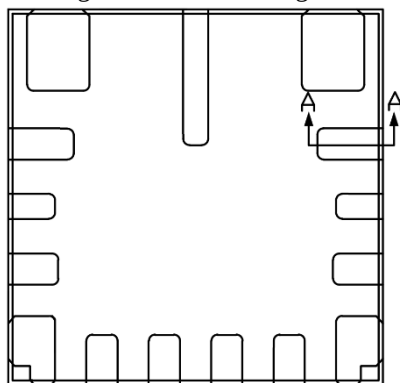


This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. ADI contact information is listed below.

PIN Title:	Product Information Notice for Package Outline Drawing Change of Selected Products in Flip Chip QFN Package
Publication Date:	27-Jun-2025
Effectivity Date:	27-Jun-2025 (the earliest date that a customer could expect to receive changed material)
Revision Description:	Initial Release.

Description Of Change:

- 1) Wetting height will be changed from 0.1mm min to 0.065mm min.
- 2) Wetting width will be changed from 0.01mm min - 0.06mm max to 0.01mm min - 0.1mm max.



Reason For Change:

This is a document update only based on process tolerance. POD update still complies with JEDEC package outline drawing.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no impact to fit, form, function, quality, or reliability.

Summary of Supporting Information:

Comments:

THIS IS NOT A PCN. This is an advisory of a minor update to the Package Outline Drawing.

Supporting Documents:

ADI Contact Information:

For questions on this PIN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file

Appendix B – Revision History:

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	27-Jun-2025	27-Jun-2025	Initial Release.